ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® INCLUSTRIES®	annockburn. Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration	ion of the succession of the s	ubstances s all lowe	within the manuf r level materials	acturer lister	d item. Note e manufactu	e: if the item is an a rrer has engineering	ssembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distributed			k	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					als and Mfg Information			
Supplier Information													
Company name*	npany name* Company unique ID			Unique ID Authority					Respo	Response Date*			
onsemi	mi								2025-	2025-06-08			
Contact Name	Title - Contact			]	Phone - Contact*				Emai	Email - Contact*			
Product-Env-Stewards	-Env-Stewards Product Enviro Compliance			NA				Prod	Product-Env-Stewards@onsemi.com				
uthorized Representative* Title - Representative				Phone - Representative*				Emai	Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA			Prod	Product-Env-Stewards@onsemi.com					
Requester Item Number N	Ifr Item Number	Mfr Item Name			Effective Date	e Version	1	Manufacturing Site		Weight*	UOM	Unit Type	
N	SCP114ASN270T1G	14ASN270T1G 300 mA CMOS LE Vout=2.7V			2025-06-08		(	CN1		13.65	mg	Each	
Manufacturing Proccess Information													
Terminal Plating / Grid Array Material	Terminal Base Alloy J-		J-STD-020 MSL	Rating	Peak Pro	cess Body Temperature Max Time at Peak		Peak Tempe	Temperature Number of Reflow Cycles		cles		
Matte Tin (Sn) - annealed CU Alloy 1		1		260		С	30	sec	onds 3				
Comments													
level 1 - maximum time at peak temperature du	ring soldering is 10-3	0 seconds											
For more information regarding material comp	osition please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.12	mg	Supplier	Silicon (Si)	7440-21-3		0.12	mg
Lead Frame 5	5.78	mg	Supplier	Silver (Ag)	7440-22-4		0.526	mg
			В	Nickel (Ni)	7440-02-0		2.127	mg
			Supplier	Iron (Fe)	7439-89-6		2.9189	mg
			Supplier	Copper (Cu)	7440-50-8		0.2081	mg
Mold Compound-Black	7.34	mg		Epoxy resin	proprietary data		0.367	mg
			Supplier	Phenolic Resin	Proprietary Data		0.367	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1468	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0367	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.4225	mg
Plating	0.39	mg	Supplier	Tin (Sn)	7440-31-5		0.39	mg
Wire Bond - Cu	0.02	mg	Supplier	Copper (Cu)	7440-50-8		0.02	mg